Processes and Materials III

Packaging is a completed process in its own right

- It needs very special materials even the lowly black plastic that dominates the appearance of chips is a sophisticated material!
- It also includes extensive testing of the chip.

Chip	
Cleaning/wet chemistry 4 Oxidation/Heating 5 Deposition 7 Mechanical work 6 Lithograpy/Laser cut 2 Dry etch 1 Controls/Tests 11	Materials O ₂ , N ₂ H ₂ O Solvents Polymers Leadframe (Cu, Ni, Au, Fe) Au wire
All wire Solder	